

QORVO

SiC JFET Division

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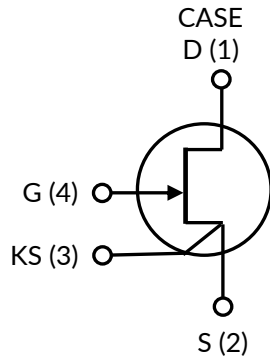
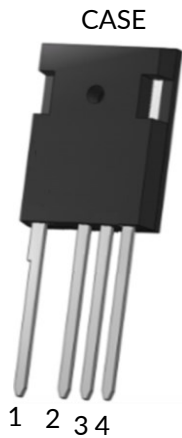
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Silicon Carbide (SiC) JFET - EliteSiC, Power N-Channel, TO-247-4L, 1200 V, 7.1 mohm

Rev. D, January 2025

DATASHEET

UF3N120007K4S



Description

Qorvo's UF3N120007K4S is a 1200 V, 7.1mΩ high-performance Gen 3 normally-on SiC JFET transistor. This device exhibits ultra-low on resistance ($R_{DS(on)}$) in a TO-247-4L package, making it an ideal fit to address the challenging thermal constraints of solid-state circuit breakers and relay applications. Additionally, the JFET is a robust device technology capable of the high-energy switching required in circuit protection applications.

Features

- ◆ Single digit on-resistance
- ◆ Operating temperature: 175°C (max)
- ◆ High pulse current capability
- ◆ Excellent device robustness
- ◆ Silver-sintered die attach for excellent thermal resistance
- ◆ RoHS compliant
- ◆ AECQ Qualified

Typical applications

- ◆ Solid State / Semiconductor Circuit Breaker
- ◆ Solid State / Semiconductor Relay
- ◆ Battery Disconnects
- ◆ Surge Protection
- ◆ Inrush Current Control
- ◆ Induction heating

Part Number	Package	Marking
UF3N120007K4S	TO-247-4L	UF3N120007K4S



Maximum Ratings

Parameter	Symbol	Test Conditions	Value	Units
Drain-source voltage	V_{DS}		1200	V
Gate-source voltage	V_{GS}	DC	-30 to +3	V
		AC ¹	-30 to +30	V
Continuous drain current ²	I_D	$T_C < 112^\circ\text{C}$	120	A
Pulsed drain current ³	I_{DM}	$T_C = 25^\circ\text{C}$	550	A
Power dissipation	P_{tot}	$T_C = 25^\circ\text{C}$	789	W
Maximum junction temperature	$T_{J,max}$		175	$^\circ\text{C}$
Operating and storage temperature	T_J, T_{STG}		-55 to 175	$^\circ\text{C}$
Max. lead temperature for soldering, 1/8" from case for 5 seconds	T_L		250	$^\circ\text{C}$

1. +30V AC rating applies for turn-on pulses <200ns applied with external $R_G > 1\Omega$.

2. Limited by bondwires

3. Pulse width t_p limited by $T_{J,max}$

Thermal Characteristics

Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Thermal resistance, junction-to-case	$R_{\theta JC}$			0.15	0.19	$^\circ\text{C}/\text{W}$

Electrical Characteristics ($T_J = +25^\circ\text{C}$ unless otherwise specified)

Typical Performance - Static

Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Drain-source breakdown voltage	BV_{DS}	$V_{GS} = -20\text{V}, I_D = 1\text{mA}$	1200			V
Total drain leakage current	I_{DSS}	$V_{DS} = 1200\text{V}, V_{GS} = -20\text{V}, T_J = 25^\circ\text{C}$		20	300	μA
		$V_{DS} = 1200\text{V}, V_{GS} = -20\text{V}, T_J = 175^\circ\text{C}$		100		
Total gate leakage current	I_{GSS}	$V_{GS} = -20\text{V}, T_J = 25^\circ\text{C}$		15	300	μA
		$V_{GS} = -20\text{V}, T_J = 175^\circ\text{C}$		55		μA
Drain-source on-resistance	$R_{DS(on)}$	$V_{GS} = 2\text{V}, I_D = 100\text{A}, T_J = 25^\circ\text{C}$		7.1		$\text{m}\Omega$
		$V_{GS} = 0\text{V}, I_D = 100\text{A}, T_J = 25^\circ\text{C}$		8.6	11	
		$V_{GS} = 2\text{V}, I_D = 100\text{A}, T_J = 175^\circ\text{C}$		15.5		
		$V_{GS} = 0\text{V}, I_D = 100\text{A}, T_J = 175^\circ\text{C}$		17.8		
Gate threshold voltage	$V_{G(th)}$	$V_{DS} = 5\text{V}, I_D = 320\text{mA}$	-9.3	-7	-4.7	V
Gate resistance	R_G	$f = 1\text{MHz}, \text{open drain}$		0.54		Ω

Typical Performance - Dynamic

Parameter	Symbol	Test Conditions	Value			Units
			Min	Typ	Max	
Input capacitance	C_{iss}	$V_{DS} = 800\text{V}, V_{GS} = -20\text{V}$ $f = 100\text{kHz}$		8110		pF
Output capacitance	C_{oss}			368		
Reverse transfer capacitance	C_{rss}			358		
Effective output capacitance, energy related	$C_{oss(er)}$	$V_{DS} = 0\text{V to } 800\text{V}, V_{GS} = -20\text{V}$		403		pF
C_{OSS} stored energy	E_{oss}	$V_{DS} = 800\text{V}, V_{GS} = -20\text{V}$		130		μJ
Total gate charge	Q_G	$V_{DS} = 800\text{V}, I_D = 100\text{A}, V_{GS} = -18\text{V to } 0\text{V}$		830		nC
Gate-drain charge	Q_{GD}			520		
Gate-source charge	Q_{GS}			120		

Typical Performance Diagrams

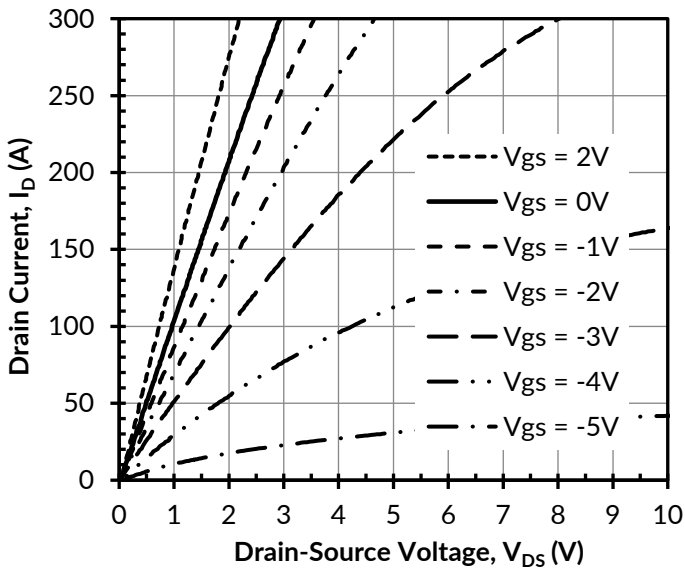


Figure 1. Typical output characteristics at $T_j = -55^\circ\text{C}$, $t_p < 250\mu\text{s}$

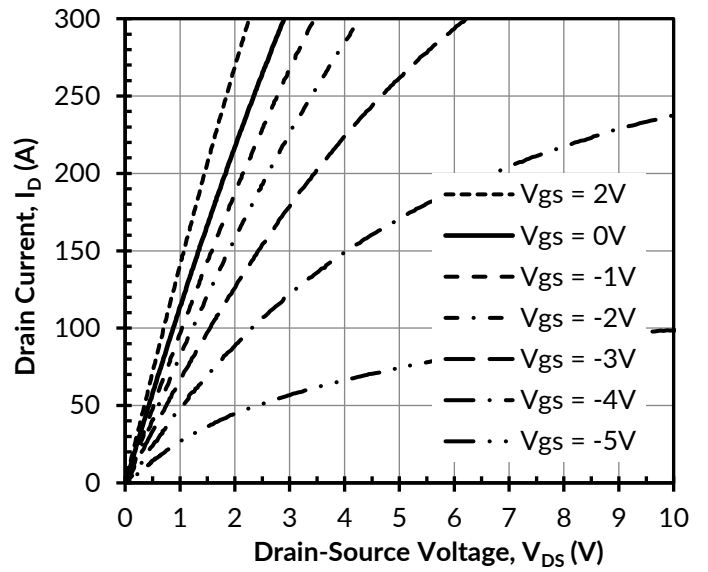


Figure 2. Typical output characteristics at $T_j = 25^\circ\text{C}$, $t_p < 250\mu\text{s}$

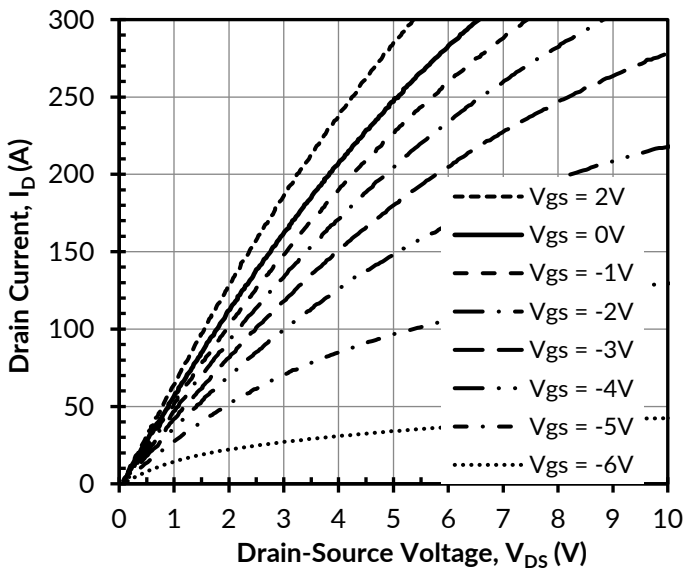


Figure 3. Typical output characteristics at $T_j = 175^\circ\text{C}$, $t_p < 250\mu\text{s}$

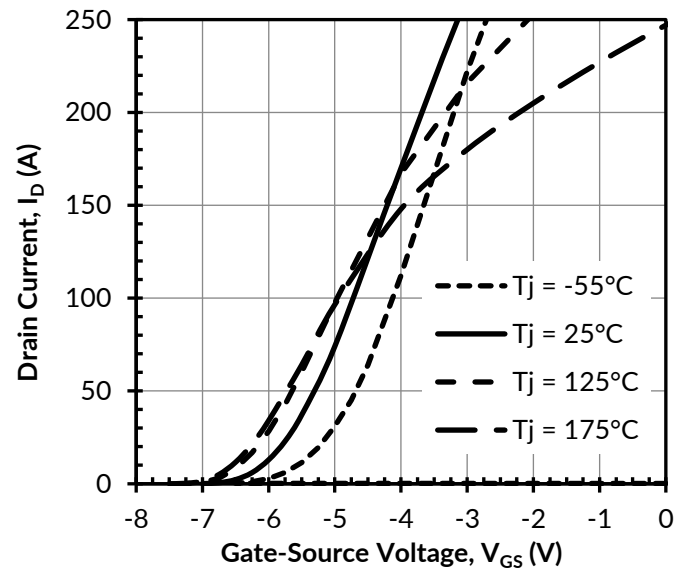


Figure 4. Typical transfer characteristics at $V_{DS} = 5\text{V}$

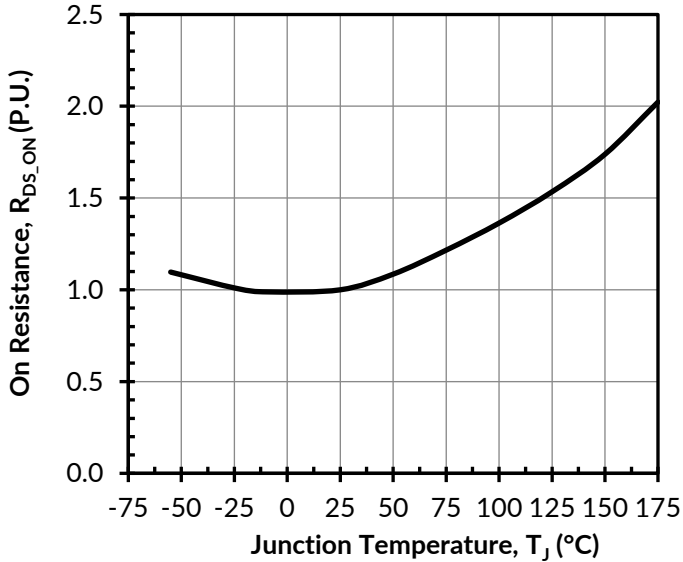


Figure 5. Normalized on-resistance vs. temperature at $V_{GS} = 0V$ and $I_D = 100A$

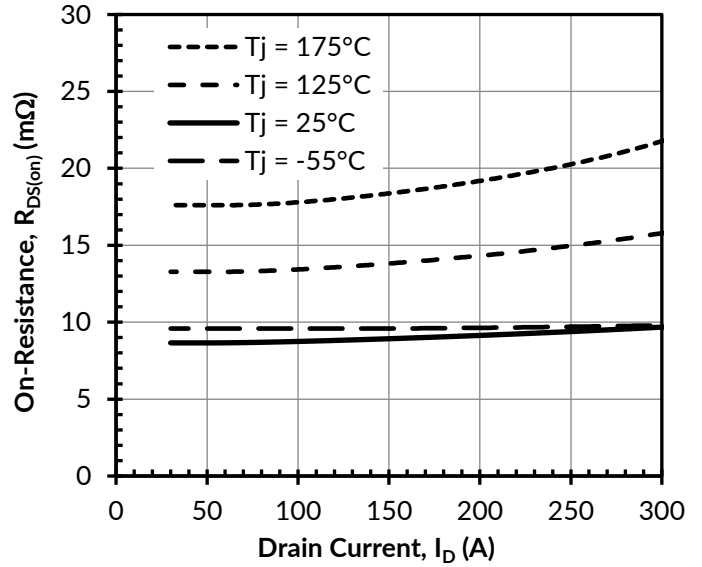


Figure 6. Typical drain-source on-resistances at $V_{GS} = 0V$

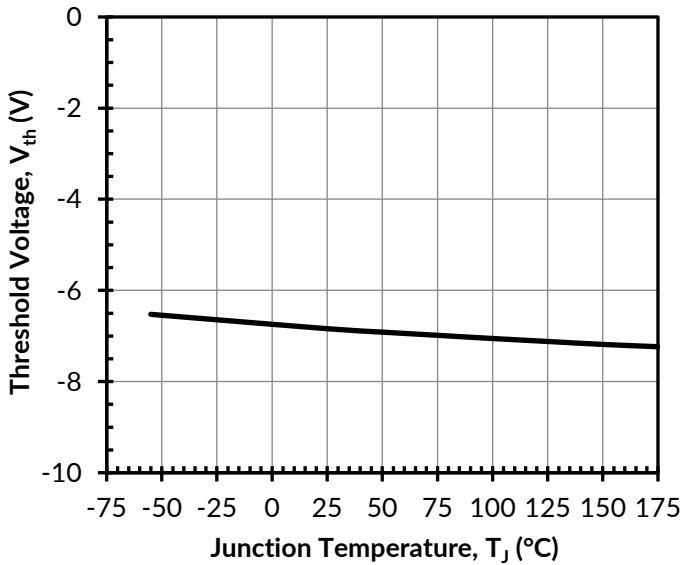


Figure 7. Threshold voltage vs. junction temperature at $V_{DS} = 5V$ and $I_D = 320mA$

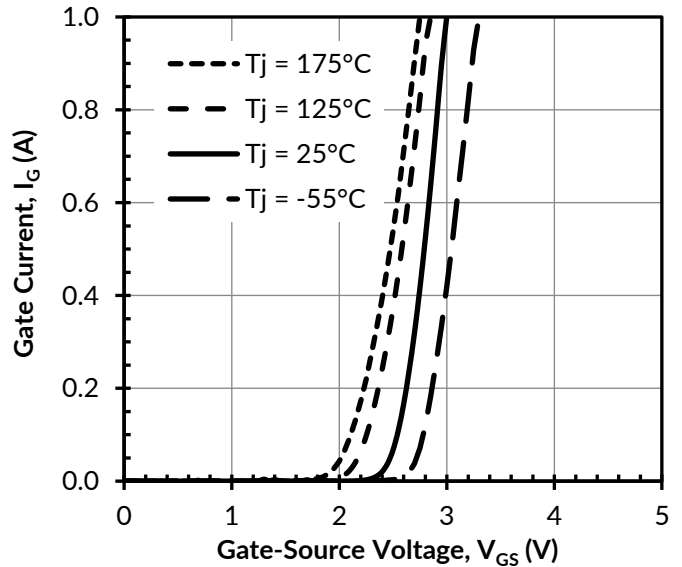


Figure 8. Typical gate forward current at $V_{DS} = 0V$

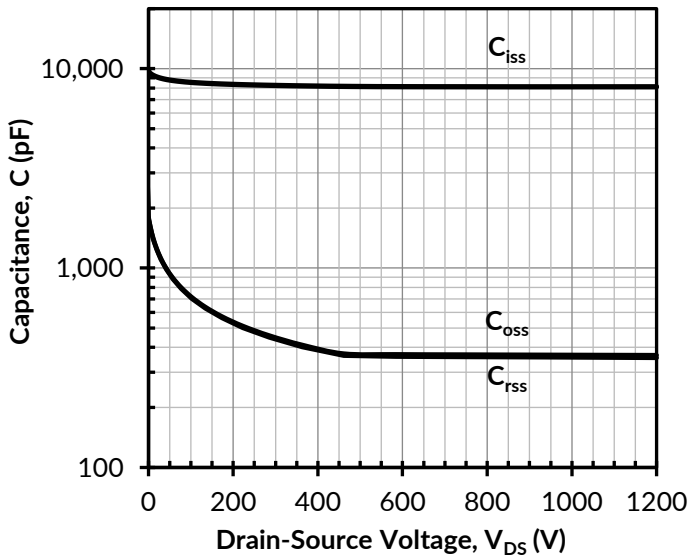


Figure 9. Typical capacitances at $f = 100\text{kHz}$ and $V_{GS} = -20\text{V}$

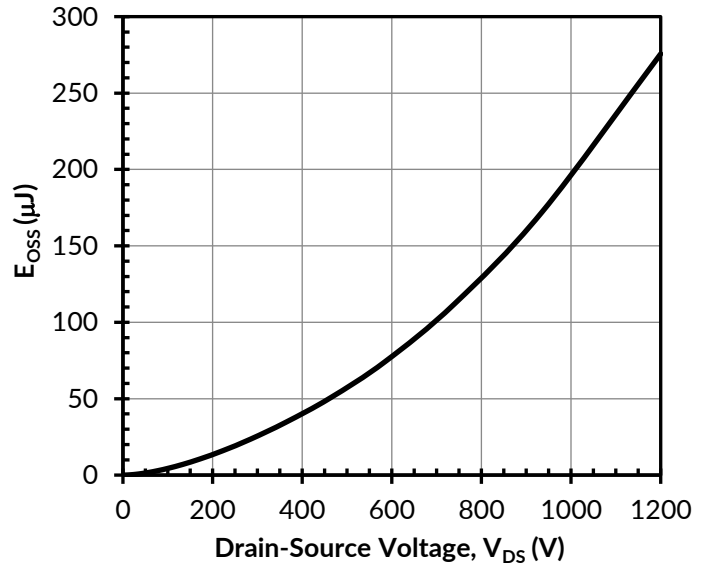


Figure 10. Typical stored energy in C_{OSS} at $V_{GS} = -20\text{V}$

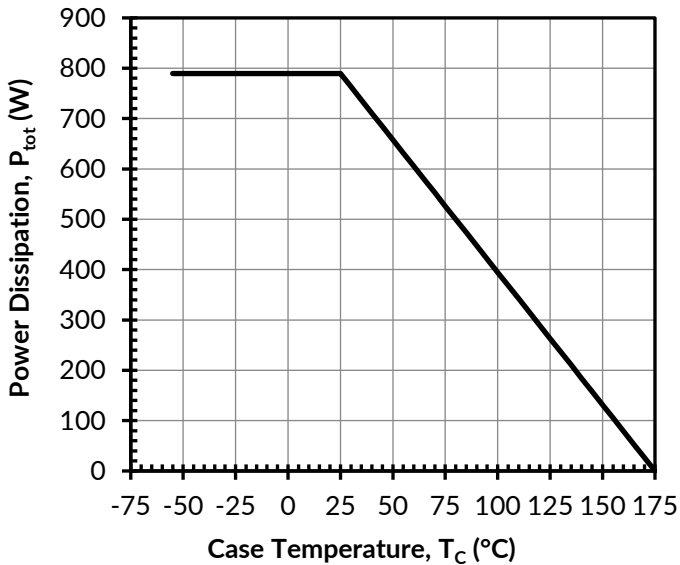


Figure 11. Total power Dissipation

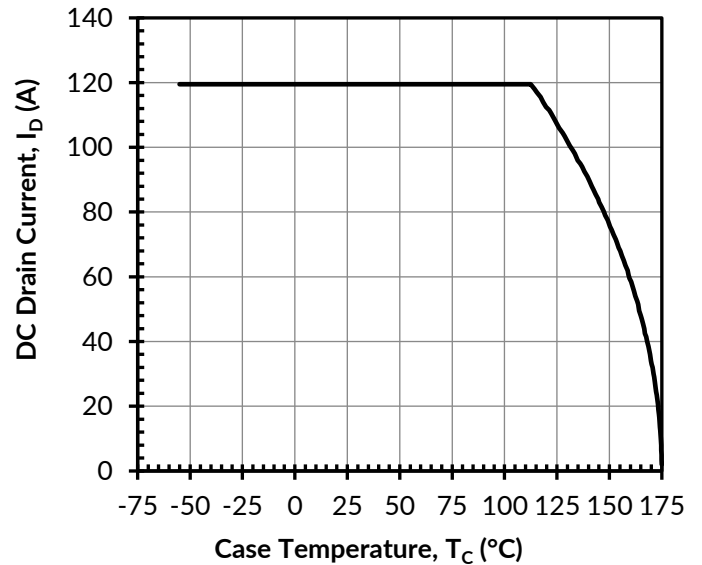


Figure 12. DC drain current derating

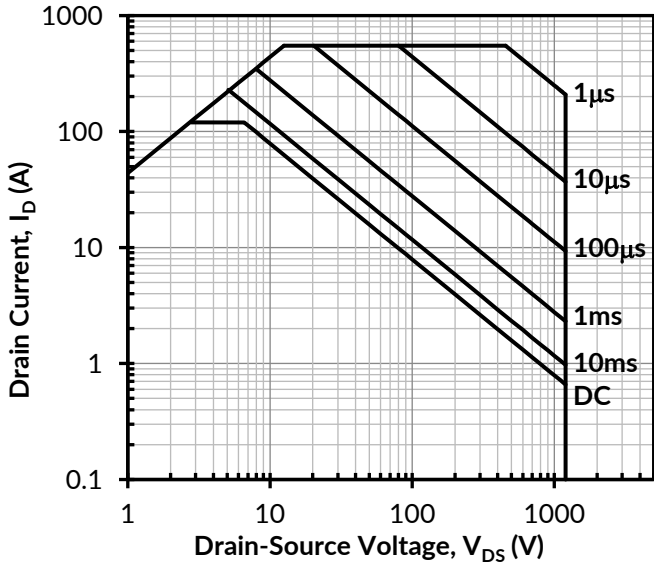


Figure 13. Safe operation area at $T_C = 25^\circ\text{C}$, Parameter t_p

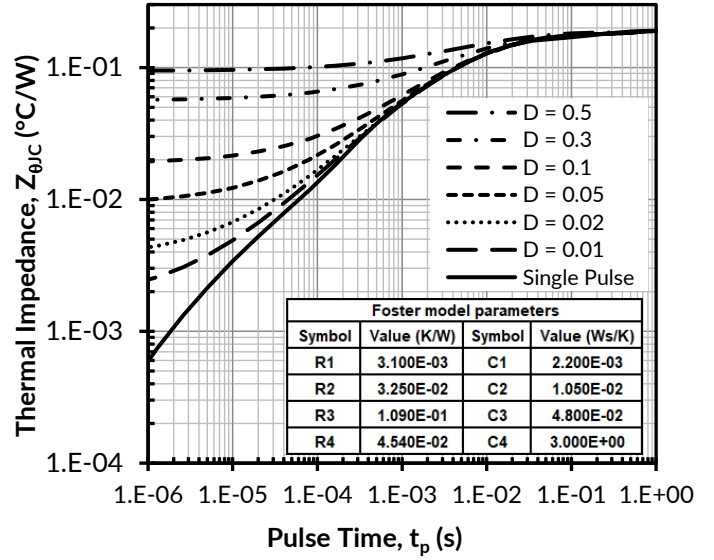


Figure 14. Maximum transient thermal impedance

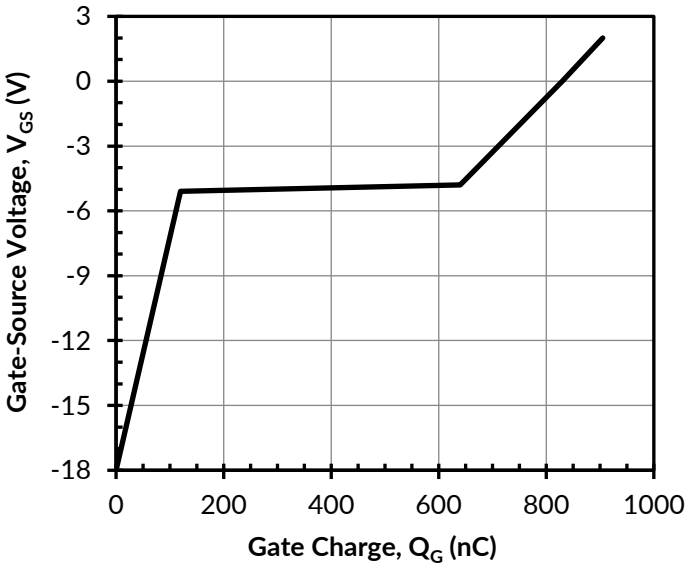
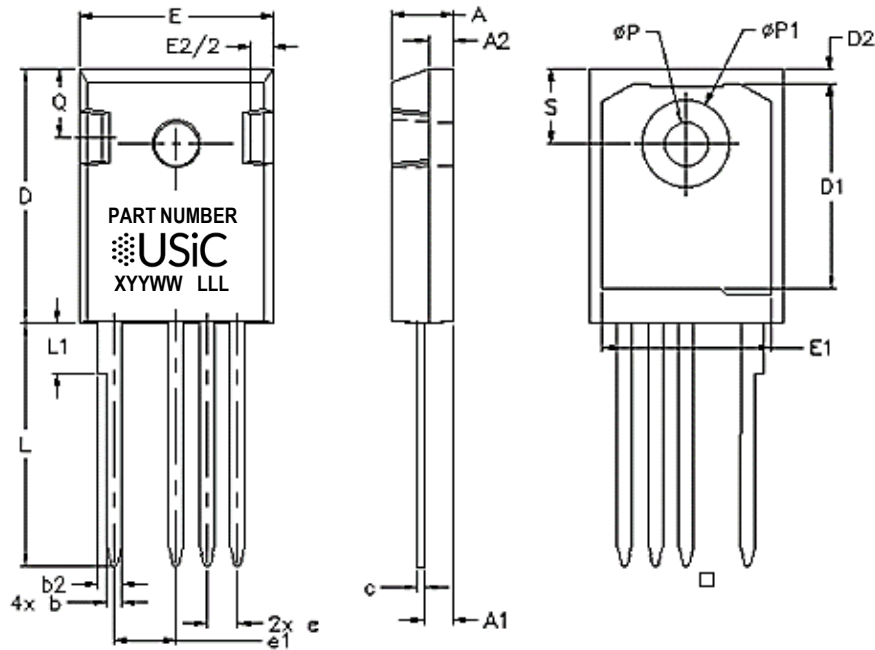


Figure 15. Typical gate charge at $V_{DS} = 800\text{V}$ and $I_D = 100\text{A}$

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PACKAGE OUTLINE



DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.185	0.209	4.7	5.31
A1	0.087	0.102	2.21	2.59
A2	0.059	0.098	1.5	2.49
b	0.039	0.055	0.99	1.4
b2	0.065	0.094	1.65	2.39
c	0.015	0.035	0.38	0.89
D	0.819	0.845	20.8	21.46
D1	0.515	-	13.08	-
D2	0.02	0.053	0.51	1.35
E	0.61	0.64	15.49	16.26
e	0.100 BSC		2.54 BSC	
e1	0.19	0.21	4.83	5.33
E1	0.53	-	13.46	-
E2	0.14	0.16	3.56	4.06
L	0.78	0.8	19.81	20.32
L1	-	0.177	-	4.5
ΦP	0.14	0.144	3.56	3.66
$\Phi P1$	0.278	0.291	7.06	7.39
Q	0.212	0.244	5.38	6.2
S	0.243 BSC		6.17 BSC	



PART MARKING

TO-247-4L PACKAGE OUTLINE, PART MARKING AND TUBE SPECIFICATIONS

PART NUMBER

The logo for USiC, featuring a circular pattern of black dots on the left and the text "USiC" in a large, bold, black sans-serif font on the right.
XYYWW LLL

PART NUMBER = REFER TO
DS_PN DECODER FOR DETAILS

X = ASSEMBLY SITE

YY = YEAR

WW = WORK WEEK

LLL = LOT ID

PACKING TYPE

ANTI-STATIC TUBE

QUANTITY /TUBE : 30 UNITS

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